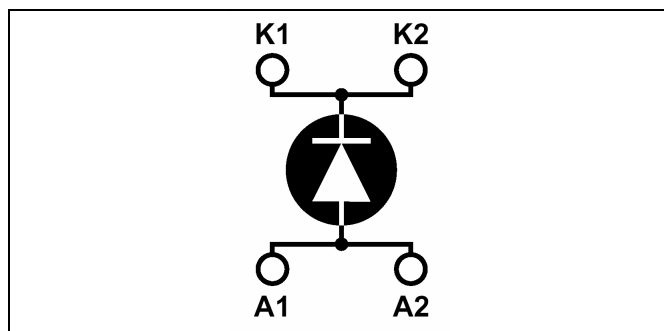


Single diode Power Module

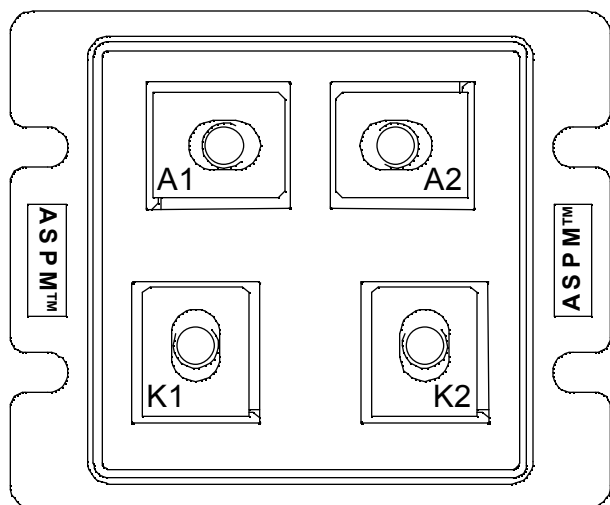
$$V_{CES} = 400V$$

$$I_C = 500A @ T_c = 80^{\circ}C$$



Application

- Anti-Parallel diode
 - Switchmode Power Supply
 - Inverters
- Snubber diode
- Uninterruptible Power Supply (UPS)
- Induction heating
- Welding equipment
- High speed rectifiers
- Electric vehicles



Features

- Ultra fast recovery times
- Soft recovery characteristics
- Very low stray inductance
- High blocking voltage
- High current
- Low leakage current

Benefits

- Low losses
- Low noise switching
- Direct mounting to heatsink (isolated package)
- Low junction to case thermal resistance
- RoHS Compliant

Absolute maximum ratings

Symbol	Parameter			Max ratings	Unit	
V _R	Maximum DC reverse Voltage			400	V	
V _{RRM}	Maximum Peak Repetitive Reverse Voltage					
I _{F(AV)}	Maximum Average Forward Current	Duty cycle = 50%	T _c = 25°C	500	A	
			T _c = 80°C	500		
I _{F(RMS)}	RMS Forward Current			850		
I _{FSM}	Non-Repetitive Forward Surge Current		T _j = 25°C	5000		

CAUTION: These Devices are sensitive to Electrostatic Discharge. Proper Handling Procedures Should Be Followed. See application note APT0502 on www.microsemi.com

All ratings @ $T_j = 25^\circ\text{C}$ unless otherwise specified

Electrical Characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Test Conditions</i>		<i>Min</i>	<i>Typ</i>	<i>Max</i>	<i>Unit</i>
V_F	Diode Forward Voltage	$I_F = 500\text{A}$				1.5	V
		$I_F = 1000\text{A}$			1.5		
		$I_F = 500\text{A}$	$T_j = 150^\circ\text{C}$			1.3	
I_{RM}	Maximum Reverse Leakage Current	$V_R = 400\text{V}$	$T_j = 25^\circ\text{C}$			2500	μA
			$T_j = 150^\circ\text{C}$			5000	
C_T	Junction Capacitance	$V_R = 200\text{V}$			800		pF

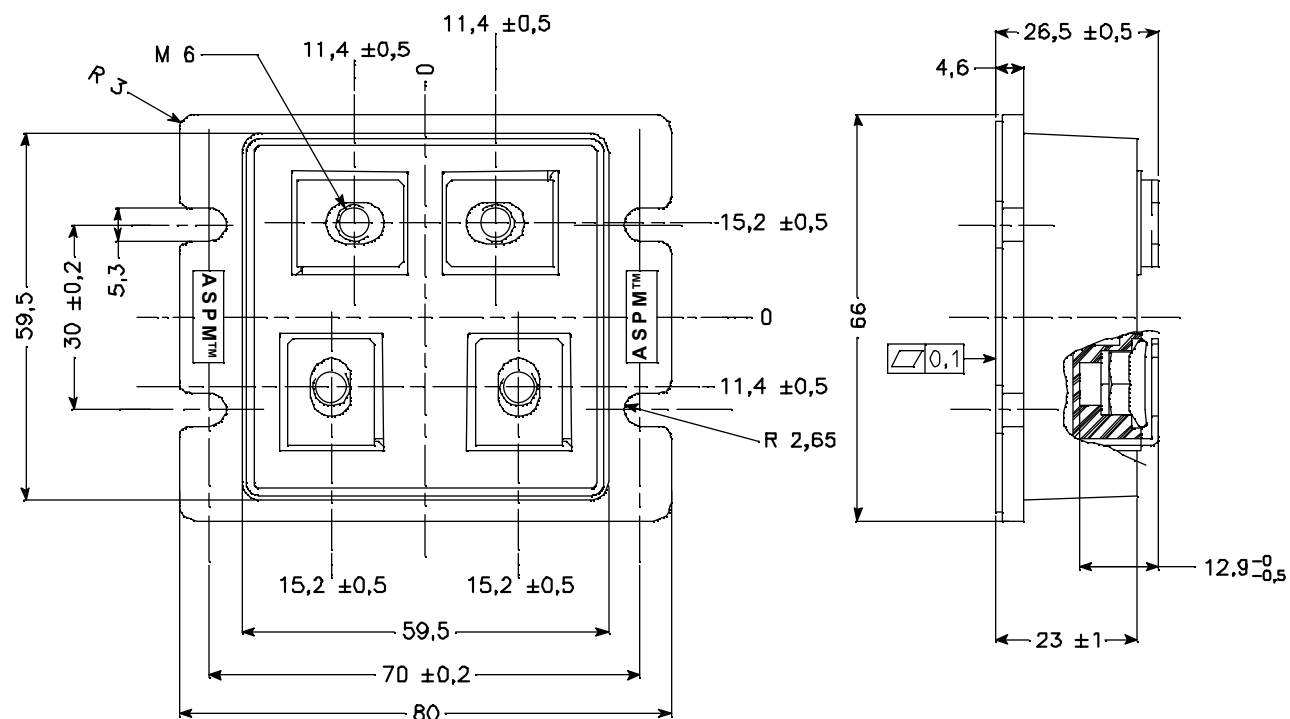
Dynamic Characteristics

Dynamic Characteristics		Test Conditions		Min	Typ	Max	Unit
t _{rr1}	Reverse Recovery Time	I _F =1 A, V _R =30V di/dt = 15A/μs	T _j = 25°C			50	ns
t _{rr2}			T _j = 25°C			120	
t _{rr3}			T _j = 100°C			260	
t _{fr1}	Forward Recovery Time	I _F = 500 A V _R = 240 V di/dt=1000A/μs	T _j = 25°C		210		ns
t _{fr2}			T _j = 100°C		220		
I _{RRM1}	Reverse Recovery Current		T _j = 25°C			50	A
I _{RRM2}			T _j = 100°C			120	
Q _{rr1}	Reverse Recovery Charge		T _j = 25°C			3	μC
Q _{rr2}			T _j = 100°C			15.6	
V _{fr1}	Forward Recovery Voltage		T _j = 25°C		19		V
V _{fr2}			T _j = 100°C		19		
d _{IM} /dt	Rate of Fall of Recovery Current		T _j = 25°C		1200		A/μs
			T _j = 100°C		1800		

Thermal and package characteristics

<i>Symbol</i>	<i>Characteristic</i>	<i>Min</i>		<i>Typ</i>	<i>Max</i>	<i>Unit</i>
R_{thJC}	Junction to Case Thermal Resistance				0.08	$^\circ\text{C}/\text{W}$
V_{ISOL}	RMS Isolation Voltage, any terminal to case $t = 1\text{ min}, I_{isol} < 1\text{mA}, 50/60\text{Hz}$	2500				V
T_j	Operating junction temperature range	-40			150	$^\circ\text{C}$
T_{STG}	Storage Temperature Range	-40			125	
T_C	Operating Case Temperature	-40			100	
Torque	Mounting torque	To heatsink	M5	2.5	3.5	N.m
		For terminals	M6	3	4	
Wt	Package Weight				250	g

LP4 Package outline (dimensions in mm)



Microsemi reserves the right to change, without notice, the specifications and information contained herein

Microsemi's products are covered by one or more of U.S. patents 4,895,810 5,045,903 5,089,434 5,182,234 5,019,522 5,262,336 6,503,786 5,256,583 4,748,103 5,283,202 5,231,474 5,434,095 5,528,058 and foreign patents. U.S. and Foreign patents pending. All Rights Reserved.